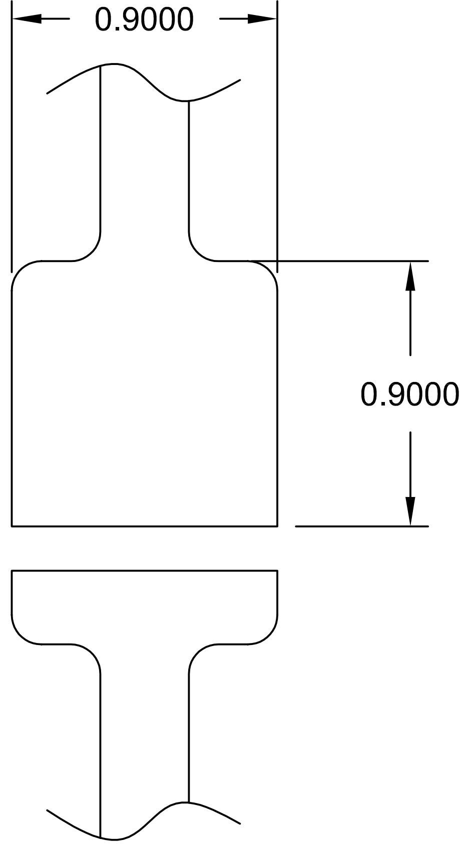
# CIRTEK ELECTRONICS CORPORATION

116 East Avenue, Phase V, SEZ Laguna Technopark
Binan, Laguna, Philippines


## PRODUCT INFORMATION

| | |
|---|---|
| Customer : | |
| Device : | Device ID : |
| Die Size : | Wafer Material : |
| Package Type: SOD-323 | No. of Wires : |

## MATERIAL INFORMATION

| | |
|---|---|
| Leadframe : Alloy42 with spot Ag | Pad Size : 0.90x0.90mm |
| Epoxy : | Wire size : |
| Molding Compound : | Lead Finish : |

## MARKING INSTRUCTION

| | |
|---|---|
| TOP : | BOTTOM : |

BONDING DIAGRAM NO.

| REF. BONDING DIAGRAM NO. | SCALE<br>not to scale |
|---|---|

| DRAWN BY: | REVIEWED BY : |
|---|---|

SPECIAL INSTRUCTIONS :

| REVISION NO. | | | APPROVALS | | |
|---|---|---|---|---|---|
| REV. # | DESCRIPTION | PCN # | DEPT | APPROVALS | DATE |
| | | | CUST | | |
| | | | QSM | | |
| | | | QC | | |
| | | | MFG | | |